Exploring Advanced Science & Technology

TOHOKU UNIVERSITY SCIENCE SUMMER PROGRAM 2016 July 4th to July 15th, 2016

What's TSSP?

TSSP is designed for undergraduates majoring science and engineering. It aims to provide students with insight on what world society needs based on advanced science and technology in the future and how they can contribute to society. Program participants will have an opportunity to experience lectures with facility/laboratory visits followed by a final presentation based on group work. Topics covered in this program are:

Spintronics – Computer Vision in Robotics – Robotics – Neutrinos – Carbon Nanotube – Modern Physical Chemistry – The 2011 Tohoku Earthquake and more. (Topics are subject to change.)

In addition to exploring advanced science and technology, there will be Japanese language classes and field trips to historical sites, as well as workshops in Japanese traditional culture. Students will also have many opportunities to interact with Tohoku University students.

Tohoku University

Tohoku University, located in Sendai City, was founded in 1907 as Japan's third national university. It continues to be an innovative university committed to the principles of "Research First" and "Open Doors". For details, please visit: <u>http://www.tohoku.ac.jp/en/</u>

About Sendai

With a population of 1 million, Sendai (located around 300 km northeast of Tokyo -only 1.5 hours by "*Shinkansen*" bullet train) is the largest city in the Tohoku region and is known as the City of Trees (*Mori no Miyako*).



PROGRAM

SCHEDULE

[TSSP]: Monday 4th July, 2016 to Friday 15th July, 2016 Applying for two consecutive terms (ex. TSSP and TUJP-2) is not allowed.



ELIGIBILITY

- Full-time undergraduate students at designated partner universities of Tohoku University (Listed as 'Designated Institutions' on the "COURSES" page.)
- Sufficient English ability (equivalent to TOEFL iBT 70 or PBT 520)
 *Students must be enrolled in their home universities during this program.
 *All classes and instructions are provided in English.

PROGRAM FEE

1 USD = 120 JPY, as of January 2016

to be paid in cash on the first day	Accommodation (¥61,100) for 13 nights. To be paid directly to the hotel when checking out	=	Total ¥81,100 (about US \$680)
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Program fee includes: tuition, field trips, homestay, certificate, and activities. Travel, accommodation, insurance, meals, and personal daily expenses should be paid individually.

SCHOLARSHIP OPPORTUNITY

A Japan Student Services Organization (JASSO) scholarship may be awarded to those who meet the requirements below and attend the entire program. You can apply by completing the JASSO scholarship application form available from our website.

Minimum requirement for JASSO scholarship:	<u>GPA of 2.30 of 3.00</u> (JASSO's GPA calculation methods)			
Scholarship amount:	¥80,000			

CREDITS

On completing the program successfully, students should be eligible to earn 4ECTS*.

* 1ECTS is equivalent to 25 hours of work. ETCS credits are a value allocated to course units to describe the student workload required to complete them. Please note that those credits are not conferred at Tohoku University, so each participant needs to negotiate with his/her home institution with the transcripts we issue.



COURSES

The participants will have an opportunity to participate in 8 lectures with facility/ laboratory visits. At the end of the program students will make presentations on the topics given by each lecturer.

1 st WEEK							
	Mon.	Tue.	Wed.	Thu.	Fri.	Sat.	Sun.
TSSP	4-Jul	5-Jul	6-Jul	7-Jul	8-Jul	9-Jul	10-Jul
AM	Welcome	Japanese	Language	Lectures & Lab Visits			
	Ceremony &	Lunch			Field Work	Free	
PM Orientation		Lectures & Lab Visits		Culture	Preparation		
2 nd WEEK							
TSSP	11-Jul	12-Jul	13-Jul	14-Jul	15-Jul	16-Jul	17-Jul
AM	Lectures & Lab Visits				Presentation		
PM	Lecture & Lab Visit	Culture	Group Work	Field Trip	& Farewell party		

Designated Institutions

Schedule and contents are subject to change without prior notice.

Korea	Australia	Finland
KAIST	Australian National U.	Aalto U.
Pohang U. of Science and Technology	U. of Melbourne	Tampere U. of Technology
Seoul National U.	U. of New South Wales	U. of Oulu
Sungkyunkwan U.	U. of Sydney	Russia
China	France	Far Eastern Federal U.
Northeastern U.	École Centrale de Lille	Moscow State U.
Tsinghua U.	École Centrale de Lyon	Novosibirsk State U.
Wuhan U. of Technology	École Centrale de Marseille	Saint Petersburg State U.
Zhejiang U.	École Centrale de Nantes	U. of Nizhni Novgorod
Hong Kong	École Centrale de Paris	United States of America
Hong Kong UST	(CentraleSupélec)	Case Western Reserve U.
Singapore	U. of Grenoble	Michigan State U.
National U. of Singapore	U. of Rennes 1	Pennsylvania State U.
Thailand	Germany	Purdue U.
Chiang Mai U.	Karlsruhe I of Technology	U. of California, Berkeley
Chulalongkorn U.	RWTH Aachen U.	U. of California, Davis
KMIT Ladkrabang	Technical U. of Berlin	U. of California, Irvine
KMUT Thonburi	U. of Göttingen	U. of California, Los Angels
Suranaree U. of Technology	U. of Heidelberg	U. of California, Marced
Thammasat U.	Netherlands	U. of California, Riverside
Thai-Nichi Institute of Technology	Delft U. of Technology	U. of California, San Diego
Indonesia	U. of Twente	U. of California, San Francisco
Bandung I of Technology	Switzerland	U. of California, Santa Barbara
Bogor Agricultural U.	EPFL	U. of California, Santa Cruz
Gadjah Mada U.	ETH Zurich	U. of Hawaii at Manoa
U. of Brawijaya	Sweden	U. of Maryland
U. of Indonesia	Chalmers U. of Technology	U. of North Carolina at Charlotte
Malaysia	Royal I of Technology (KTH)	U. of Washington
U. of Malaya	Stockholm University	Canada
/ -	, Umeå U.	U. of Ottawa
	Uppsala U.	U. of Waterloo
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APPLICATION

- → For Students: Contact your international affairs office to apply. Students must be nominated by their home institutions. Nominated students are required to fill in the online application form and upload the required documents no later than the deadline below.
- → For International Affairs Office Staff: Please nominate students from those interested, and send a list of candidates via email to: <u>tujp@grp.tohoku.ac.jp</u>. Also please provide a link for the online application form sent separately to only those nominated. Applicants are required to apply via the online application form and upload the following supporting documents by the deadline below.



Required documents:

- 1. Applicant's portrait photo (4 cm x 3 cm)
- 2. Transcript from the previous academic year in English
- 3. Photocopy of passport (page with applicant's photo)
- 4. Personal Statement (300-500 words/reasons for applying)
- 5. Copy of English language ability certificate and scores
- 6. Application Form for Japan Student Services Organization (JASSO) Scholarship with hand-written signature (if applicable)

Program	TSSP
Deadline for Application	March 31, 2016 (JST)
Admission Notification	Late April, 2016
Arrival	July 3, 2016
Welcome Ceremony	July 4, 2016
Farewell Ceremony	July 15, 2016
Accommodation Check-out	July 16, 2016

ACCOMMODATION

Each student will stay in a furnished bedroom with a unit bathroom at a hotel located in a convenient area. Breakfast is not included but is available upon request (¥800/meal). Participants will need to pay accommodation fees at the end of the program directly to the hotel (¥61,100 total).

MEDICAL INSURANCE

<u>Summer program participants are required to buy travel insurance in their own country BEFORE coming to</u> <u>Japan</u>. Students will be solely responsible for any accidents that occur while staying in Japan. Their insurance must cover death and medical care expenses not only due to accidental bodily injury but also for sickness.

VISAS

Those who need a visa to enter Japan should indicate this on their application forms. Tohoku University will provide an invitation letter to admitted students. Passport holders of certain countries do not need a visa to enter Japan for periods of less than 90 days.

CONTACT

Tohoku University Global Learning Center/Student Exchange Division 41 Kawauchi, Aoba-ku, Sendai, Miyagi 980-8576, Japan Website: <u>http://www.insc.tohoku.ac.jp/english/short/tssp/</u> Email: <u>tusp@grp.tohoku.ac.jp</u>

